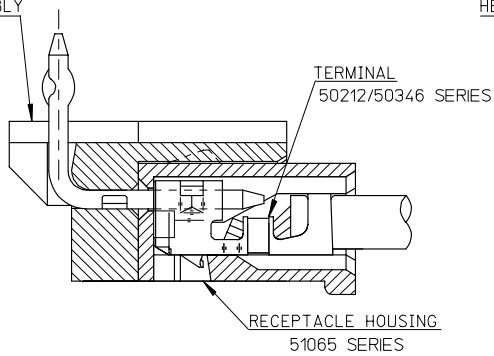


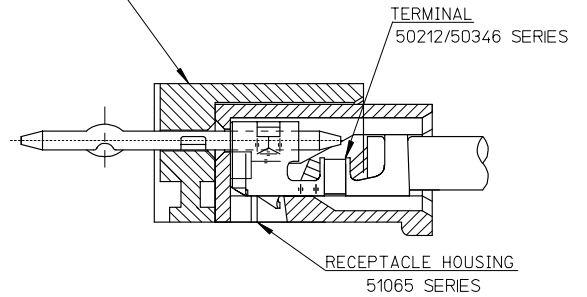
10 9 8 7 6 5 4 3 2 1

HEADER HOUSING ASSEMBLY
53254SERIES

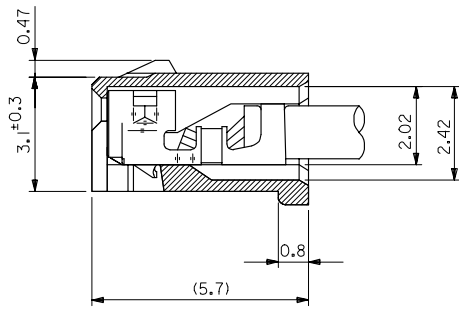


51065シリーズ/53254シリーズ 嵌合状態図 参考
51065 SERIES/53254 SERIES MATED DRAWING (REF.)

HEADER HOUSING ASSEMBLY
53253SERIES



51065シリーズ/53253シリーズ 嵌合状態図 参考
51065 SERIES/53253 SERIES MATED DRAWING (REF.)



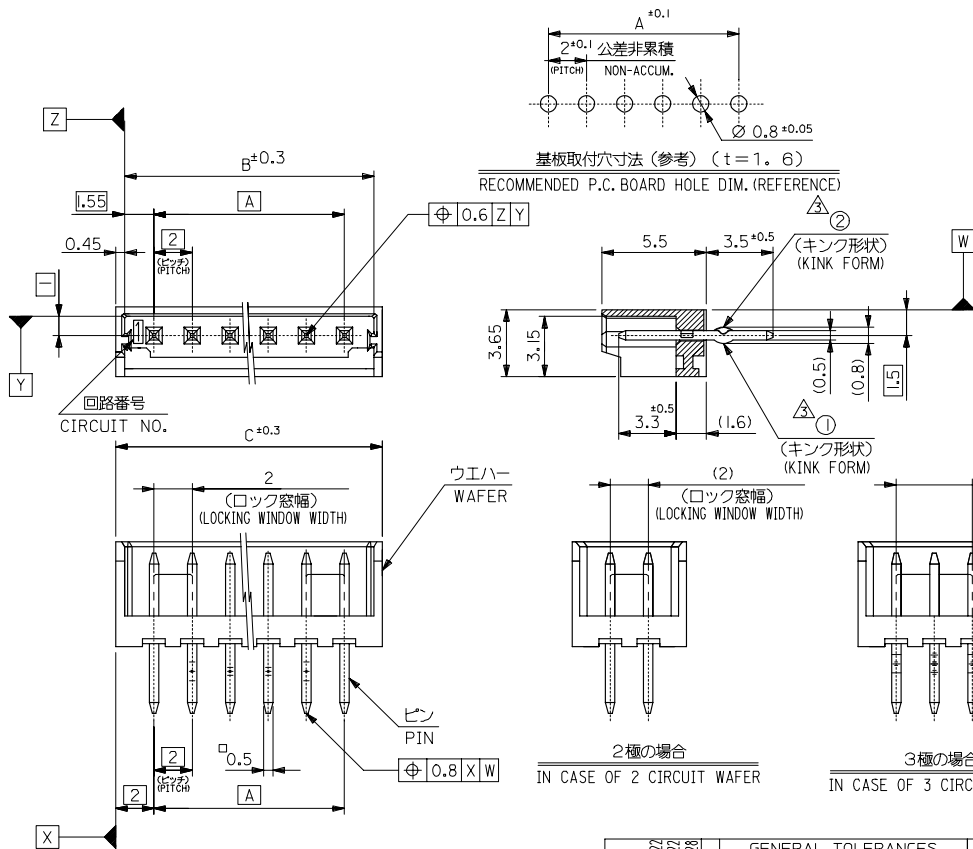
ターミナル装着状態図
TERMINAL ASS'Y DWG.

RELEASED EC NO: J2008-2041 DRWN: AOYAGI 2007/11/12 CHKD: HARUYAMA 2007/11/22 APPR: NUKITA 2007/11/22	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY Y. AOYAGI	DATE 2007/11/13	TITLE NEW 2.0 W/B CONN. 51065/53253OR51065/53254 MOLEX INCORPORATED DOCUMENT NO. SD-51065-006 SHEET NO. 1 OF 1		
	10 OVER 30 UNDER	± 0.25	CHECKED BY N. UKITA	DATE 2007/11/13			
	30 OVER	± 0.3	APPROVED BY N. UKITA	DATE 2007/11/13			
	ANGULAR	± 1 °	MATERIAL NO.		SEE TABLE		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

fb_frame_A3_1_ME_S
Rev. E 2006/04/15

9 8 7 6 5 4 3 2 1 EN-02JA(021)

10 9 8 7 6 5 4 3 2 1



注記 NOTES

1. 嵌合相手: 51065 シリーズ
MATE WITH: 51065 SERIES
 2. 材質 MATERIAL
ウエハー: 66ナイロン, UL94V-0
WAFER: 66NYLON, UL94V-0
ピン: 黄銅, 錫メッキ
PIN: BRASS, TIN(Sn) PLATING
 - △ キングは下記表の位置及び形状に付加のこと。2極はキング無し。
KINK TO BE APPLIED AS FOLLOWS,
2 CIRCUIT HAS NO KINK.
- | 極数 CKT | 回路番号 CKT NO. | 1 | 2 | 3 | 4 | 5 | N-2 | N-1 | N |
|--------|-----------------|---|---|---|---|---|-----|-----|---|
| 6 極以上 | MORE THAN 6 CKT | — | ① | ② | — | — | ② | ① | — |
| 5 極 | 5 CKT | ① | ② | — | ② | ① | | | |
| 4 極 | 4 CKT | ① | ② | ① | | | | | |
| 3 極 | 3 CKT | ① | ② | ① | | | | | |
4. 本製品は、53253-**10の鉛フリー品です。
THIS PRODUCT IS LEAD FREE OF 53253-**10.
 5. 梱包仕様 PACKAGING
53253-**70 トレー TRAY
53253-**50 ポリ袋 POLYBAG

32	31.1	28	53253-1550	53253-1570	15
30	29.1	26	-1450	-1470	14
28	27.1	24	-1350	-1370	13
26	25.1	22	-1250	-1270	12
24	23.1	20	-1150	-1170	11
22	21.1	18	-1050	-1070	10
20	19.1	16	-0950	-0970	9
18	17.1	14	-0850	-0870	8
16	15.1	12	-0750	-0770	7
14	13.1	10	-0650	-0670	6
12	11.1	8	-0550	-0570	5
10	9.1	6	-0450	-0470	4
8	7.1	4	-0350	-0370	3
6	5.1	2	53253-0250	53253-0270	2
C	B	A	MATERIAL NO.	MATERIAL NO.	極数
			MODEL NO. 53253-**70/**50		

REVISED IEC NO. J2005-2396 DRAWN BY CHIKUDA APPR. NIKITA 2005/02/22 2005/02/22 2005/02/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY T. TSUBOI	DATE '04/01/15	TITLE NEW 2.0 WIRE TO BOARD CONN. WAFER ASSY (ST.) -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY S. MARUYAMA	DATE '04/01/15	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE '04/01/15	DOCUMENT NO. SD-53253-001		
	ANGULAR ±3°		MATERIAL NO. SEE CHART		SHEET NO. 1 OF 1		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					